

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L2 | 2 | ("5864177" "6005778").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/16 14:31 |
| L3 | 1615 | 257/777.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:32 |
| L4 | 3 | ("4132856" "4809053" "5631497").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/16 14:34 |
| L5 | 14 | ("5804872").URPN. | USPAT | OR | ON | 2005/09/16 14:34 |
| L7 | 2535 | 257/718-720.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:52 |
| L8 | 1711 | 7 and (substrate or board) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:41 |
| L9 | 1259 | 7 and ((circuit adj substrate) or board) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:39 |
| L11 | 1246 | 9 not 3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:39 |
| L12 | 1380 | 257/796,675.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:39 |
| L13 | 1153 | 11 not L12 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:40 |
| L15 | 2375 | 257/712.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 15:21 |

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|-----|------|--|---|----|----|------------------|
| L16 | 963 | 15 and ((chip or die) with heat) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:53 |
| L17 | 821 | 16 and (substrate or board or PCB) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 15:21 |
| L18 | 1554 | 15 not 17 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 15:05 |
| L19 | 2341 | 257/705-707.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 15:21 |
| L20 | 1930 | 19 and (substrate or board or PCB) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 15:22 |
| L21 | 1805 | 20 and heat | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 15:55 |
| L22 | 536 | 19 not 21 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 16:01 |
| L23 | 5477 | (chip or die) near (stack or stacked or stacking) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 16:02 |
| L24 | 354 | 23 with heat | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 16:02 |
| L29 | 2 | "20040156173" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 16:23 |

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|-----|--------|---|---|----|----|------------------|
| S1 | 4723 | heat adj spreader | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:30 |
| S2 | 2940 | S1 and (chip or semiconductor) and packag\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:12 |
| S3 | 146 | (epoxy adj mold adj compound) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:32 |
| S4 | 14 | S2 and S3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:46 |
| S5 | 1380 | 257/796,675.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 19:32 |
| S6 | 1199 | S5 and (heat) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:47 |
| S7 | 757 | S6 and chip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:47 |
| S8 | 136 | S7 and S1 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:47 |
| S9 | 121474 | (chip or semiconductor) with (package or packaging) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:14 |
| S10 | 1796 | S9 and (chip near3 stack) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:14 |

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|-----|--------|---|---|----|----|------------------|
| S11 | 129678 | (chip or semiconductor or die) with (package or packaging) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:14 |
| S12 | 3075 | S9 and ((chip or die) with stack) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:14 |
| S13 | 987 | S12 and ((chip or die) with heat) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:14 |
| S14 | 192 | S13 and PCB | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:22 |
| S15 | 13 | "6242285" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:04 |
| S16 | 12602 | (die or chip) with (die or chip) with (heat adj (sink or spreader)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:05 |
| S17 | 126 | S16 and ((second or upper or top) adj (pCB or (circuit adj board))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:06 |
| S18 | 1 | Jeong near (Nyeon\$1Sik) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:20 |
| S19 | 1 | Jeong near2 Nyeon | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:21 |
| S20 | 1 | Jeong near3 Nyeon | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:21 |

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|-----|--------|---|---|----|----|------------------|
| S21 | 760210 | package or packaging | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:23 |
| S22 | 7434 | S21 and ((stack or stacked) with (die or chip)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:23 |
| S23 | 1524 | (upper or top) adj ((printed adj circuit) or PCB) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:26 |
| S24 | 5497 | (second or first or upper or top) adj ((printed adj circuit) or PCB) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:26 |
| S25 | 4592 | S24 and (second or first or lower or bottom) adj ((printed adj circuit) or PCB) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:27 |
| S26 | 39 | S22 and S25 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 18:27 |
| S27 | 1615 | 257/777.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 14:32 |